

COMPLETE THIS FORM TO INITIATE SUPPLIER SCOUTING

MEPNN Supplier Scouting Opportunity Synopsis

*The submitting entity agrees to notify NIST MEP of the status of actions taken as a result of this scouting instance within 30 days after receiving a results report. For instances where the submitting entity is an MEP Center submitting on behalf of a client, the MEP Center agrees to notify NIST MEP on behalf of their client. For instances where the submission is direct from federal/state agencies or is a private company, the submitting federal/state agency or private company entity agrees to notify NIST MEP. Notification should be via email to scouting@nist.gov, indicating the following:

- Contact with matches identified in report complete and supply contract awarded, process complete
- Contact with matches identified in report complete and no supply contract awarded, process complete
- Contact with matches identified in report complete and supply negotiations underway, process in progress
- Contact with matches identified in report underway; supply negotiations not yet begun; process in progress
- Contact with matches identified in report not yet begun, process in progress
- Contact with matches identified in report will not occur within the next 6-months, process complete

ICP RIE for Etching Silicon with Hydrogen Bromide and Chlorine

_____ 30 _____ days

Opportunities will be posted for 30 days unless specified

Item to be Scouted

Please describe the item application/ the end use of item.* Provide the item number if applicable: (N95 Mask vs Protective Mask).

The National Institute of Standards and Technology (NIST) seeks information on commercial vendors that can provide an inductively coupled plasma (ICP) reactive ion etcher for etching silicon with hydrogen bromide (HBr) and chlorine (Cl2) to support nanofabrication in the Center for Nanoscale Science and Technology (CNST) user facility. The system will be sited and used as a shared resource accessible to researchers from industry, academia, NIST, and other government agencies in the CNST NanoFab. This ICP silicon etching system is a pattern transfer tool that uses HBr or Cl2 and other chemicals to fabricate micron- and nano-scale structures in silicon substrate. Applications include fabricating nano-semiconductor and nano-photonics devices.

2022-136

Supplier Scouting Number (NIST MEP use)

333242

Scouting customer/product [NAICS Code](#), if known

TECHNICAL INFORMATION:	1. Supplier Information	a. Type of supplier being sought*
		<input checked="" type="checkbox"/> Manufacturer <input type="checkbox"/> Contract Manufacturer <input type="checkbox"/> Distributor <input type="checkbox"/> Other _____
	2. Summary of Technical Specifications and Performance Requirements:	b. Reason for scouting submission*
		<input type="checkbox"/> 2nd Supplier <input type="checkbox"/> Price <input type="checkbox"/> Re-shore <input type="checkbox"/> Past supplier no longer available <input type="checkbox"/> New Product Startup <input checked="" type="checkbox"/> Other _____
a. Describe the manufacturing processes (elaborate to provide as much detail as possible).*		
Item to be purchased as a standalone unit		
b. Provide dimensions / size / tolerances / performance specifications for the item.*		
<p>this ICP system is a pattern transfer tool that uses an inductively coupled plasma to fabricate micron- and nano-scale structures in silicon, primarily using HBr, Cl2 and other etching gases. This new ICP silicon etcher will be used to minimize the system down time, improve the process repeatability and add new NanoFab's etching process capabilities. 2. Tool configuration: The system must be equipped with following components: 1) A load-lock that transfers the samples in and out of the process chamber. 2) A process chamber that is compatible with reactive chemicals such as HBr, Cl2, Argon (Ar), Oxygen (O2) and other etching gases. 3) An ICP source that operates from 0 to 2000 W. 4) A RIE electrode that operates from 0 to 500 W or higher. 5) A pumping system that is compatible with HBr, Cl2 and other chemistries. 6) Software that supports both manual and automatic operations. 7) Safety interlocks to keep users safe. 3. Wafer compatibility and handling: 1) The system shall be able to process substrates with various sizes including 75 mm, 100 mm, 150 mm and 200 mm substrate. 2) The system shall have a wafer carrier loading system which can adapt various wafer sizes without opening the process chamber. 3) The wafer carrier loading system shall have wafer top clamping and backside helium cooling. 2. Established process library: 1) The system shall have established processes for etching silicon structures by using HBr, Cl2 and other etching gases. 2) Established process documentation shall include process parameters such as etch rate, selectivity, and profile with scanning electron microscope pictures.</p>		

		<p>c. List required materials needed to make the product, including materials of product components.*</p> <p>Item to be purchased as a standalone unit</p>
	<p>2. Summary of Technical Specifications and Performance Requirements cont:</p>	<p>d. Are there applicable certification requirements?* <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No Please explain</p> <p>e. Are there applicable regulations?* <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No Please explain</p> <p>f. Are there any other standards, requirements, etc.?* <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No Please explain</p> <p>g. Additional Comments: Is there other information that would impact the item's performance or usefulness? Please explain.</p>
<p>BUSINESS INFORMATION:</p>	<p>3. Volume and Pricing</p> <p>4. Delivery Requirements:</p> <p>5. Addit</p>	<p>3a. Estimated potential business volume (i.e., # Units Per Day, Month, Year) *:</p> <p>One unit</p> <p>b. Estimated target price / unit cost information (flexible and negotiable <u>not</u> accepted) *:</p> <p>\$700,000.00</p> <p>a. When is it needed by? (Immediate, 30 Days, 6 months, etc.)*</p> <p>ASAP</p> <p>b. Describe packaging requirements (i.e., individually/group packaging)*</p> <p>Flexible</p> <p>c. Where will this item be shipped? *</p> <p>NIST, 100 Bureau Drive, Gaithersburg, MD 20899</p> <p>Is there other information you would like to include?</p>

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Photos or diagrams of the item (helpful but not required).

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